



TSMC run schedule 2026

December 11, 2025 – v1.2

Technology	Run	Foundry ref	Fab	Reserve before	Signed quote/PO before	Dry run GDS	Final GDS*	Tape-out	Estimated shipment date*
7nm CMOS Logic or RF FinFET***	10086	TMWB84	15	Dec 23	Feb 6	Mar 11	Apr 5	Apr 7	Aug 6
	The 7nm Cybershuttle deadline(s) for the second half of 2026 will be known in March '26								
16nm CMOS Logic or RF FinFET Compact**	10078	TMWB78	14	Oct 24 (2025)	Dec 4 (2025)	Jan 5	Jan 29	Feb 2	May 1
	10079	TMWB79	14	Dec 23	Feb 6	Mar 11	Apr 5	Apr 7	Jul 4
	10080	TMWB80	14	Feb 25	Apr 2	May 4	May 28	Jun 1	Aug 28
	10081	TMWB81	14	Apr 27	Jun 11	Jul 13	Aug 6	Aug 10	Nov 6
	10082	TMWB82	14	Jun 30	Aug 6	Sep 7	Oct 1	Oct 5	Jan 2 (2027)
	10083	TMWB83	14	Aug 3	Oct 1	Nov 2	Nov 26	Nov 30	Feb 26 (2027)
22nm CMOS Logic or RF ULL (w/ or wo/ ReRam)	10070	TMWB70	15	Nov 25 (2025)	Jan 2	Feb 4	Mar 1	Mar 3	May 30
	10071	TMWB71	15	Dec 23	Feb 13	Mar 18	Apr 12	Apr 14	Jul 11
	10072	TMWB72	15	Jan 26	Mar 13	Apr 15	May 10	May 12	Aug 8
	10073	TMWB73	15	Feb 25	May 1	Jun 3	Jun 28	Jun 30	Sep 26
	10074	TMWB74	15	Apr 27	Jun 5	Jul 8	Aug 2	Aug 4	Oct 31
	10075	TMWB75	15	May 25	Jul 3	Aug 5	Aug 30	Sep 1	Nov 28
	10076	TMWB76	15	Aug 3	Sep 4	Oct 7	Nov 1	Nov 3	Jan 30 (2027)
	10077	TMWB77	15	Aug 31	Oct 2	Nov 4	Nov 29	Dec 1	Feb 27 (2027)

* Shipment date is an estimation. Additional cycle time of (1~3 weeks) might be required. See shipment guidelines.

** Provide final GDS two weeks earlier in case of IP merge. In case of LVS or other services are required, please reach out to epsmc@imec.be at the purchase order stage.

*** The estimated shipment date for RF FinFET Compact (0.8/1.8V) will be 2 days later.

Technology	Run	Foundry ref	Fab	Reserve before	Signed quote/PO before	Dry run GDS	Final GDS**	Tape-out	Estimated shipment date*
TSMC 28nm CMOS Logic or RF HPC/HPC+	10057	TMWB61	15	Oct 24 (2025)	Dec 5 (2025)	Jan 7	Feb 1	Feb 3	Apr 26
	10058	TMWB62	15	Nov 25 (2025)	Jan 2	Feb 4	Mar 1	Mar 3	May 24
	10059	TMWB63	15	Jan 26	Mar 6	Apr 8	May 3	May 5	Jul 26
	10060	TMWB64	15	Feb 25	Apr 3	May 6	May 31	Jun 2	Aug 23
	10061	TMWB65	15	Apr 27	Jun 12	Jul 15	Aug 9	Aug 11	Nov 1
	10062	TMWB66	15	May 25	Jul 10	Aug 12	Sep 6	Sep 8	Nov 29
	10063	TMWB67	15	Aug 3	Sep 11	Oct 14	Nov 8	Nov 10	Jan 31 (2027)
	10064	TMWB68	15	Aug 31	Oct 9	Nov 11	Dec 6	Dec 8	Feb 28 (2027)
40nm CMOS Logic or MS/RF, LP (no triple gate oxide)	10046-LP	TMWB50	12	Sep 24 (2025)	Nov 20 (2025)	Dec 22 (2025)	Jan 15	Jan 19	Apr 4
	10047	TMWB51	14	Oct 24 (2025)	Dec 25 (2025)	Jan 26	Feb 19	Feb 23	May 9
	10048-LP	TMWB52	12	Dec 23	Feb 12	Mar 16	Apr 9	Apr 13	Jun 27
	10049-LP	TMWB53	14	Jan 26	Mar 12	Apr 13	May 7	May 11	Jul 25
	10050-LP	TMWB54	14	Feb 25	Apr 16	May 18	Jun 11	Jun 15	Aug 29
	10051-LP	TMWB55	14	Apr 27	Jun 11	Jul 13	Aug 6	Aug 10	Oct 24
	10052	TMWB56	12	May 25	Jul 16	Aug 17	Sep 10	Sep 14	Nov 28
	10053-LP	TMWB57	14	Jun 30	Aug 13	Sep 14	Oct 8	Oct 12	Dec 28
	10054-LP	TMWB58	14	Aug 31	Oct 15	Nov 16	Dec 10	Dec 14	Feb 27 (2027)
40nm CMOS Logic or MS/RF, GP (no triple gate oxide)	10047	TMWB52	12	Dec 23	Feb 12	Mar 16	Apr 9	Apr 13	Jun 27
	10052	TMWB56	12	May 25	Jul 16	Aug 17	Sep 10	Sep 14	Nov 28

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Technology	Run	Foundry ref	Fab	Reserve before	Signed quote/PO before	Dry run GDS	Final GDS**	Tape-out	Estimated shipment date*
7nm CMOS Logic or RF FinFET***	10086	TMWB84	15	Dec 23	Feb 6	Mar 11	Apr 5	Apr 7	Aug 6
	The 7nm Cybershuttle deadline(s) for the second half of 2026 will be known in March '26								
16nm CMOS Logic or RF FinFET Compact***	10078	TMWB78	14	Oct 24 (2025)	Dec 4 (2025)	Jan 5	Jan 29	Feb 2	May 1
	10079	TMWB79	14	Dec 23	Feb 6	Mar 11	Apr 5	Apr 7	Jul 4
	10080	TMWB80	14	Feb 25	Apr 2	May 4	May 28	Jun 1	Aug 28
	10081	TMWB81	14	Apr 27	Jun 11	Jul 13	Aug 6	Aug 10	Nov 6
	10082	TMWB82	14	Jun 30	Aug 6	Sep 7	Oct 1	Oct 5	Jan 2 (2027)
	10083	TMWB83	14	Aug 3	Oct 1	Nov 2	Nov 26	Nov 30	Feb 26 (2027)
22nm CMOS Logic or RF ULL (w/ or wo/ ReRam)	10070	TMWB70	15	Nov 25 (2025)	Jan 2	Feb 4	Mar 1	Mar 3	May 30
	10071	TMWB71	15	Dec 23	Feb 13	Mar 18	Apr 12	Apr 14	Jul 11
	10072	TMWB72	15	Jan 26	Mar 13	Apr 15	May 10	May 12	Aug 8
	10073	TMWB73	15	Feb 25	May 1	Jun 3	Jun 28	Jun 30	Sep 26
	10074	TMWB74	15	Apr 27	Jun 5	Jul 8	Aug 2	Aug 4	Oct 31
	10075	TMWB75	15	May 25	Jul 3	Aug 5	Aug 30	Sep 1	Nov 28
	10076	TMWB76	15	Aug 3	Sep 4	Oct 7	Nov 1	Nov 3	Jan 30 (2027)
	10077	TMWB77	15	Aug 31	Oct 2	Nov 4	Nov 29	Dec 1	Feb 27 (2027)

* Shipment date is an estimation. Additional cycle time of (1~3 weeks) might be required. See shipment guidelines.

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Design registration guidelines

- Single reservation for multiple chips
- No backup reservation
- Provide single GDS with all designs,
 - Enclosed with TSMC sealring + 80um scribe (post-shrink if applicable).
 - If designs are not identical, put marker in the scribe line.
 - Add dummies to the scribe line for 12-inch tape-outs.
 - Exception: multiple reservations accepted for different projects with different metal stacks or far backend.

Shipment guidelines

- The estimated shipment date is applicable for reservations with quantity <200 dies.
- If additional samples are required above 200 dies, additional cycle time of 1~3 weeks might be needed.
- Cycle time estimates are based on typical conditions. Corner wafers or SHDMiM processing requires additional cycle time.
- Optional services adding cycle time
 - Lead free & copper bumping: 4 days
 - Extra wafer thinning (thinner than 10mils): up to 12 days
 - Additional bumped wafer thinning and die saw (each 200 ea.): 5 working days

ReRam IP Merge Guidelines

- To ensure timely inclusion in the TSMC MPW when an IP merge is required, deliver the final GDS 2 weeks in advance to allow sufficient time for integration and validation.
- Why This Matters:
 - **Complete LVS Setup Required** - A fully validated LVS setup must be in place before initiating the merge process.
 - **IP-transfer** - Third-party IPs have to be transferred from the vendor to the TSMC merge team, which may introduce delays in the process.
 - **Increased Complexity with Multiple IP Instances** - Merging several IP blocks adds significant complexity and increases the risk of integration issues.
 - **Merge Errors Can Jeopardize the Deadline** - Errors discovered after merging may delay the process and reduce the likelihood of meeting the MPW schedule. TSMC requests to re-submit the merge even for minor typos or missing files

Contact our teams

Support Tape-out

For support on the tape-out submission

Support SalesOps

For support on portal, quotations, export documents, purchase orders, and design registration questions

Support EP packaging

For any question related to the Europractice packaging offer.

Support Foundry

For support on foundry libraries, PDK's (installation, flavors, bugs, ...), LVS

Release notes

- **October 22, 2025**
 - Release of v 1.0 2025
- **November 21, 2025**
 - Release of v1.1 2025
 - Clarification cycle time information slide 8
- **December 11, 2025**
 - Release of v1.2 2025
 - Clarification shipment date/ final GDS date and others */**/***



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